

How to Handle Dual Flash Architecture in MC9S08LG32

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1 Introduction

The MC9S08LG32 is a member of the low-cost, low-power, and high-performance HCS08 family of 8-bit microcontroller units (MCUs). It provides 32 KB of 8-bit flash in parts of two 16 KB blocks. Both the blocks are internally divided into 512 byte pages that are basic units for erasing the flash data.

The flash memory is intended primarily for program code storage. In-circuit programming allows the operating program to be loaded into the flash memory after final assembly of the application product. It is possible to program the entire array through the single-wire background debug interface. Because no special voltages are needed for flash erase and programming operations, in-application programming is also possible through other software-controlled communication paths.

MC9S08LG32 series MCUs contain two flash arrays; therefore program and erase operations can be conducted on one array while code executing from the other. The

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Features

security and protection features treat the two arrays as a single memory entity. It is not possible to page erase or program the array from which code is being executed. The mass erase command erases both arrays, and the blank check command checks both arrays. You cannot page erase or program both arrays at the same time.

Figure 1 shows the on-chip flash memory of MC9S08LG32 series of MCUs.

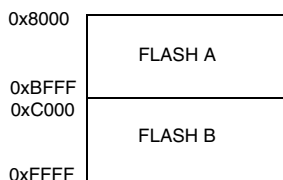


Figure 1. Flash Memory Map

2 Features

- Flash size
 - MC9S08LG32: 32,768 bytes (16,384 bytes in flash A, 16,384 bytes in flash B)
 - MC9S08LG16: 18,432 bytes (2,048 bytes in flash A, 16,384 in flash B)
- Flexible block protection
- Security feature for flash

3 Flash Configuration Registers

The flash module has six 8-bit registers for its configuration and status. Two locations (NVOPT, NVPROT) in the nonvolatile register space in flash memory are copied into corresponding high-page control registers (FOPT, FPROT) at reset.

3.1 Flash Clock Divider Register (FCDIV)

DIVLD is a read-only flag. DIV bits 6:0 may be read at any time, but can be written only one time.

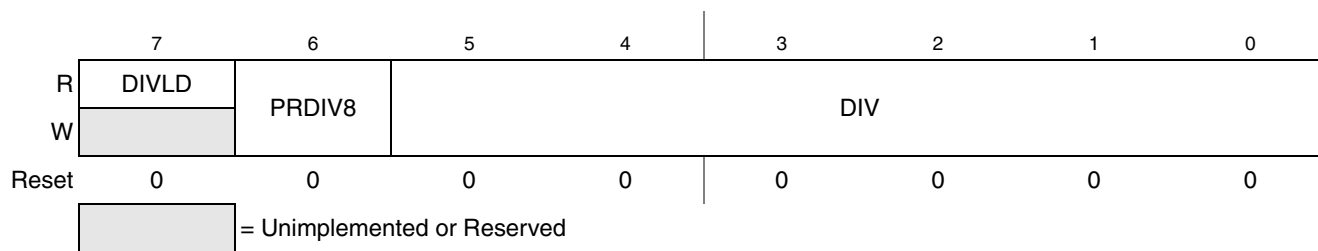


Figure 2. Flash Clock Divider Register (FCDIV)

Table 1. FCDIV Register Field Descriptions

Field	Description
7 DIVLD	Divisor Loaded Status Flag 0 FCDIV has not been written since reset; erase and program operations disabled for flash. 1 FCDIV has been written since reset; erase and program operations enabled for flash.
6 PRDIV8	Prescale (Divide) Flash Clock by 8 0 Clock input to the flash clock divider is the bus rate clock. 1 Clock input to the flash clock divider is the bus rate clock divided by 8.
5:0 DIV	Divisor for Flash Clock Divider — The flash clock divider divides the bus rate clock (or the bus rate clock divided by 8 if PRDIV8 = 1) by the value in the 6-bit DIV field plus one. See Equation 3-1 and Equation 3-2 .

$$\text{if PRDIV8} = 0 \text{ — } f_{\text{FCLK}} = f_{\text{Bus}} \div (\text{DIV} + 1) \quad \text{Eqn. 3-1}$$

$$\text{if PRDIV8} = 1 \text{ — } f_{\text{FCLK}} = f_{\text{Bus}} \div (8 \times (\text{DIV} + 1)) \quad \text{Eqn. 3-2}$$

3.2 Flash Options Register (FOPT and NVOPT)

During reset, the contents of the nonvolatile location NVOPT are copied from flash into FOPT. To change the value in this register, erase and reprogram the NVOPT location in flash memory as usual and then issue a new MCU reset.

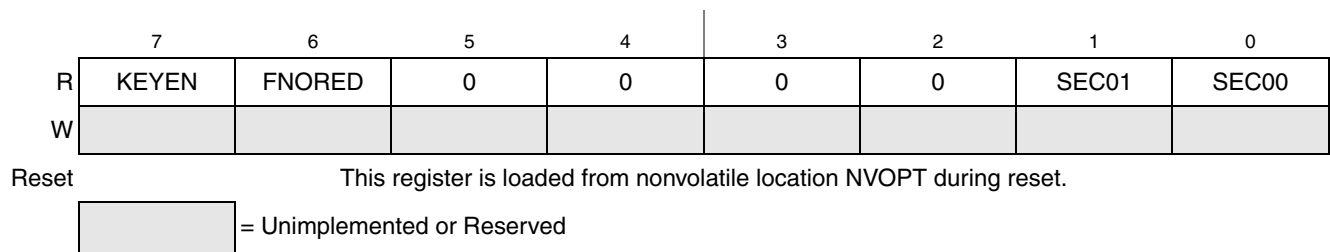


Figure 3. Flash Options Register (FOPT)

Table 2. FOPT Register Field Descriptions

Field	Description
7 KEYEN	Backdoor Key Mechanism Enable 0 No backdoor key access allowed. 1 If user firmware writes an 8-byte value that matches the nonvolatile backdoor key (NVBACKKEY through NVBACKKEY+7 in that order), security is temporarily disengaged until the next MCU reset.
6 FNORED	Vector Redirection Disable 0 Vector redirection enabled. 1 Vector redirection disabled.
1:0 SEC0[1:0]	Security State Code — This 2-bit field determines the security state of the MCU as shown in Table 3 .

 Table 3. Security States¹

SEC01:SEC00	Description
0:0	secure

Table 3. Security States¹ (continued)

SEC01:SEC00	Description
0:1	secure
1:0	unsecured
1:1	secure

¹ SEC01:SEC00 changes to 1:0 after successful backdoor key entry or a successful blank check of flash.

3.3 Flash Configuration Register (FCNFG)

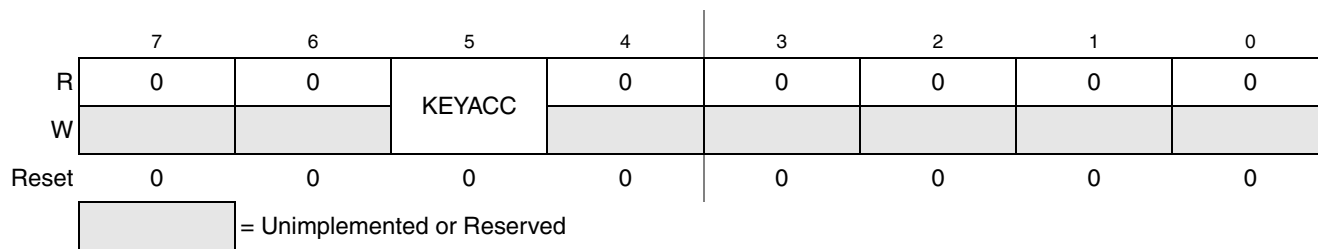


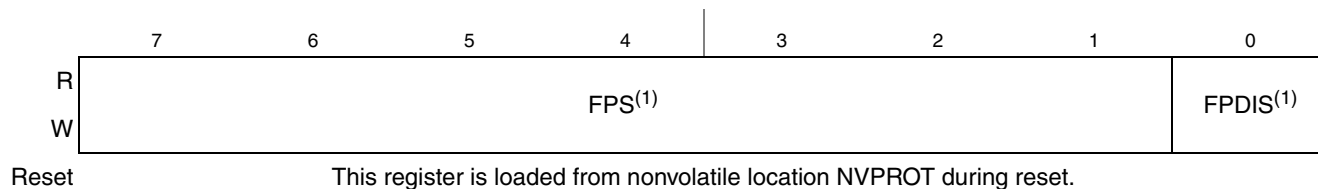
Figure 4. Flash Configuration Register (FCNFG)

Table 4. FCNFG Register Field Descriptions

Field	Description
5 KEYACC	Enable Writing of Access Key 0 Writes to flash are interpreted as the start of a flash programming or erase command. 1 Writes to NVBACKKEY (0xFFB0–0xFFB7) are interpreted as comparison key writes while writes to rest of the flash are ignored.

3.4 Flash Protection Register (FPROT and NVPROT)

During reset, the contents of the nonvolatile location NVPROT are copied from flash into FPROT. With FPDIS set, all bits are writable, but with FPDIS clear, the FPS bits are writable as long as the size of the protected region is being increased. Any FPROT write that attempts to decrease the size of the protected region, is ignored.



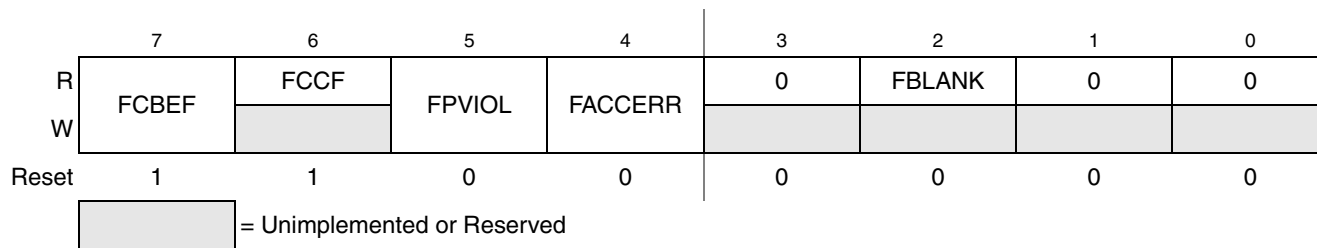
¹ Background commands can be used to change the contents of these bits in FPROT.

Figure 5. Flash Protection Register (FPROT)

Table 5. FPROT Register Field Descriptions

Field	Description
7:1 FPS	Flash Protect Select Bits — When FPDIS = 0, this 7-bit field determines the ending address of unprotected flash locations at the high address end of the flash.
0 FPDIS	Flash Protection Disable 0 Flash block specified by FPS7:FPS1 is block protected (program and erase not allowed). 1 No flash block is protected.

3.5 Flash Status Register (FSTAT)


Figure 6. Flash Status Register (FSTAT)
Table 6. FSTAT Register Field Descriptions

Field	Description
7 FCBEF	Flash Command Buffer Empty Flag —Flag to indicate the status of flash command buffer. 0 Command buffer is full (not ready for additional commands). 1 A new burst program command can be written to the command buffer.
6 FCCF	Flash Command Complete Flag —Flag to indicate the active execution of any flash command. 0 Command in progress. 1 All commands complete.
5 FPVIOL	Protection Violation Flag 0 No protection violation. 1 An attempt was made to erase or program a protected location.
4 FACCERR	Access Error Flag 0 No access error. 1 An access error has occurred.
2 FBLANK	Flash Verified as All Blank (erased) Flag 0 After a blank check command is completed and FCCF = 1, FBLANK = 0 indicates the flash array is not completely erased. 1 After a blank check command is completed and FCCF = 1, FBLANK = 1 indicates the flash array is completely erased (all 0xFF).

3.6 Flash Command Register (FCMD)

Only five command codes are recognized in normal user modes as shown in [Table 7](#).

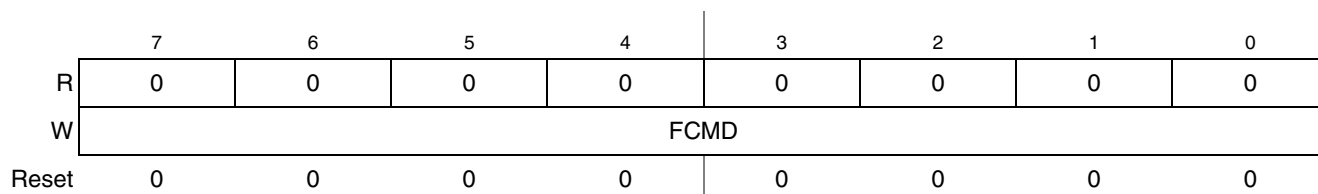


Figure 7. Flash Command Register (FCMD)

Table 7. Flash Commands

Command	FCMD	Equate File Label
Blank check	0x05	mBlank
Byte program	0x20	mByteProg
Byte program — burst mode	0x25	mBurstProg
Page erase (512 bytes/page)	0x40	mPageErase
Mass erase (all flash)	0x41	mMassErase

All other command codes are illegal and generate an access error. It is not necessary to perform a blank check command after a mass erase operation. Only blank check is required as part of the security unlocking mechanism.

4 Flash Configuration

Flash frequency is supported between 150 kHz and 200 kHz and it must be programmed in the FCDIV register. FCDIV cannot be written if the access error flag, FACCERR in FSTAT, is set. You must ensure that FACCERR is not set before writing to the FCDIV register.

Flash block has two types of registers for configuration:

1. Nonvolatile Registers—There are three registers that are mapped to flash locations that make them nonvolatile, and are used for storing the reset configuration of flash. NVOPT and NVPROT registers are copied into FOPT and FPROT respectively at the time of reset.
 - NVPROT—This register is used for protection settings of available flash. It specifies whether protection is enabled at reset. It also provides (if protection enabled) the last unprotected address in the flash memory, after which all flash locations are write-protected. In erased form, protection is disabled.
 - NVOPT—This register provides various configuration options to flash. It specifies whether or not the backdoor key entry mechanism is on and vector redirection is enabled. Most importantly, it specifies the security status of flash at the time of reset.
 - NVBACKKEY[0-7]—This provides the 8-byte key to be matched when backdoor key entry mechanism is enabled (refer to NVOPT).
2. Volatile Registers—These are the registers which control the run-time configuration of flash.
 - FCDIV—This register configures the flash frequency. Flash frequency must lie in a range of 150 kHz – 200 kHz.

- FOPT—This register is a replica of NVOPT register, whose content is copied into FOPT register at reset. This is a read-only register.
- FCNFG—This register specifies whether the writes belong to flash addresses or the backdoor key is being entered. When key writes are enabled, all access of flash locations are ignored.
- FPROT—This register is a replica of NVPROT register, whose contents are copied into FPROT register at reset. If protection is enabled, then protected area can only be increased, but not decreased. All bits in this register are writable.
- FSTAT—This register conveys the state of flash in MC9S08LG32. It has flags for access violation, command complete, buffer empty, and flash blank flags, which notify the application about the flash status.
- FCMD—This is the register in which erase, write, blank check, etc., commands are written and thus sent to flash.

5 Flash Operation

Before any program or erase command can be accepted, the flash clock divider register (FCDIV) must be written to set the internal clock for the flash module to a frequency between 150 kHz and 200 kHz. This register can be written only once, so normally this write is done during reset initialization. The bus clock frequency and FCDIV determine the frequency of FCLK. The time for one cycle of FCLK is $1/\text{FCLK}$.

6 Flash Security

The MC9S08LG32 series MCUs include circuitry to prevent unauthorized access to the contents of flash and RAM memory. When security is engaged, flash and RAM are considered secure resources. Programs executing within secure memory have normal access to any MCU memory locations and resources. Attempts to access a secure memory location with a program executing from an unsecured memory space or through the background debug interface are blocked (writes are ignored and reads return all 0s).

Security is engaged or disengaged based on the state of two nonvolatile register bits (SEC01:SEC00) in the FOPT register. During reset, the contents of the nonvolatile location NVOPT are copied from flash into the working FOPT register in high-page register space. To engage/disengage security, write SEC01:SEC00 bits in NVOPT registers with appropriate values and issue a MCU reset. The on-chip debug module cannot be enabled while the MCU is secure. The separate background debug controller can still be used for background memory access commands of unsecured resources.

Security is engaged after a mass erase command completion and the NVOPT register security bits should be programmed 0b10 to make flash permanently unsecure.

A blank check procedure immediately after a mass erase makes flash unsecure until the next reset.

7 Backdoor Key Entry Mechanism

There is a mechanism to disengage security for a single run on the fly using backdoor key entry mechanism. If KEYEN bit in NVOPT/FOPT is 1, then this method is enabled, else disabled. If KEYEN = 0, there is no way to disengage security without completely erasing all flash locations.

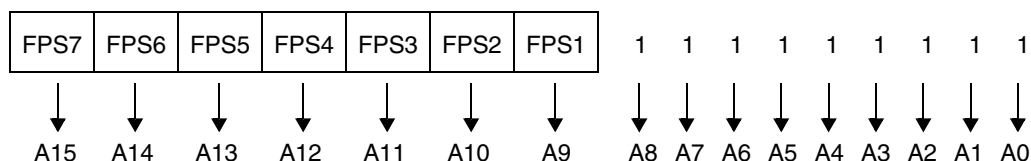
Following are the steps to disengage security temporarily:

1. Write 1 to KEYACC bit in FCNFG register to indicate that the next writes are interpreted as backdoor key.
2. Write the 8 bytes of the key at locations NVBACKKEY through NVBACKKEY+7, respectively.
3. Write 0 to KEYACC bit in FCNFG to indicate end of backdoor key entry.
4. Read security bits in FOPT. If SEC0[1:0] = 0x2, then key entered is correct and flash is unsecure until next reset, else key entered is invalid, flash is secure.

8 Flash Protection Mechanism

The block protection feature prevents the protected region of flash from program or erases. Block protection is controlled through the flash protection register (FPROT). When enabled, block protection begins at any 512-byte boundary below the last address of flash, 0xFFFF.

At reset, FPROT is loaded with the contents of NVPROT. FPROT cannot be changed directly from application software to prevent runaway programs from altering the block protection settings. Because NVPROT is within to the last 512 bytes of flash, if any amount of memory is protected, NVPROT is itself protected and cannot be altered (intentionally or unintentionally) by the application software. FPROT can be written through background debug commands that allows a protected flash memory to be erased and reprogrammed.



The FPS bits are used as the upper bits of the last address of unprotected memory. This address is formed by concatenating FPS7:FPS1 with logic 1 bits, as shown. For example, to protect the last 1536 bytes of memory (addresses 0xFA00 through 0xFFFF), the FPS bits must be set to 1111 100 that results in the value 0xF9FF as the last address of unprotected memory. In addition to programming the FPS bits to the appropriate value, FPDIS (bit 0 of NVPROT) must be programmed to logic 0 to enable block protection. Therefore, the value 0xF8 must be programmed into NVPROT to protect addresses 0xFA00 through 0xFFFF.

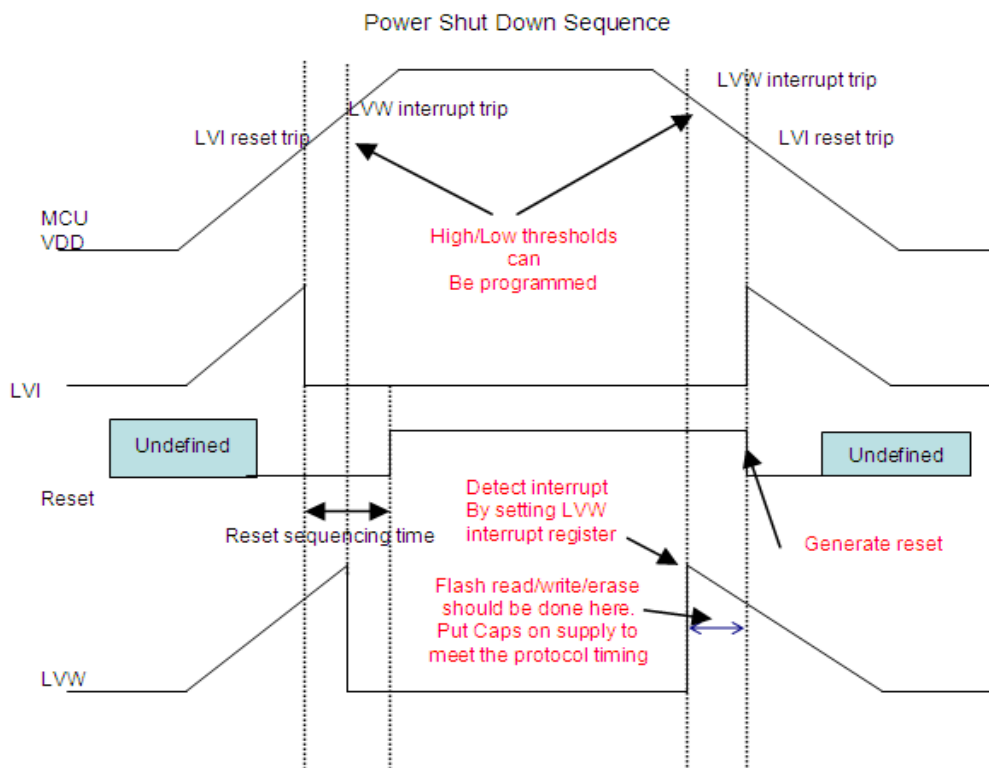
9 Special Consideration in Software

To avoid risk and to prevent loss of important data, software/application must use the LVD system inside the MC9S08LG32 series MCUs.

Here are the steps to achieve the above-mentioned protection:

1. Write SPMSC1_LVDE = 1.
2. Write SPMSC1_LVDRE = 1.
3. Write SPMSC1_LVWIE = 1.

4. Set SPMSC2_LVDV and SPMSC2_LVWV accordingly to set the LVD and LVW trip points. (Refer to *MC9S08LG32 Reference Manual* for details).
5. Insert an interrupt handler routine for low voltage warning to handle critical things in it.
6. Software must be developed to program the flash with critical data as soon as the LVW interrupt comes, and complete the programming of flash before supply reaches LVD trip point.



10 References

See [S08LG Product Summary Page](#) for more information and the documents released for MC9S08LG32.

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